

#### Foshan Evercore Optoelectronic Technology Co., Ltd.

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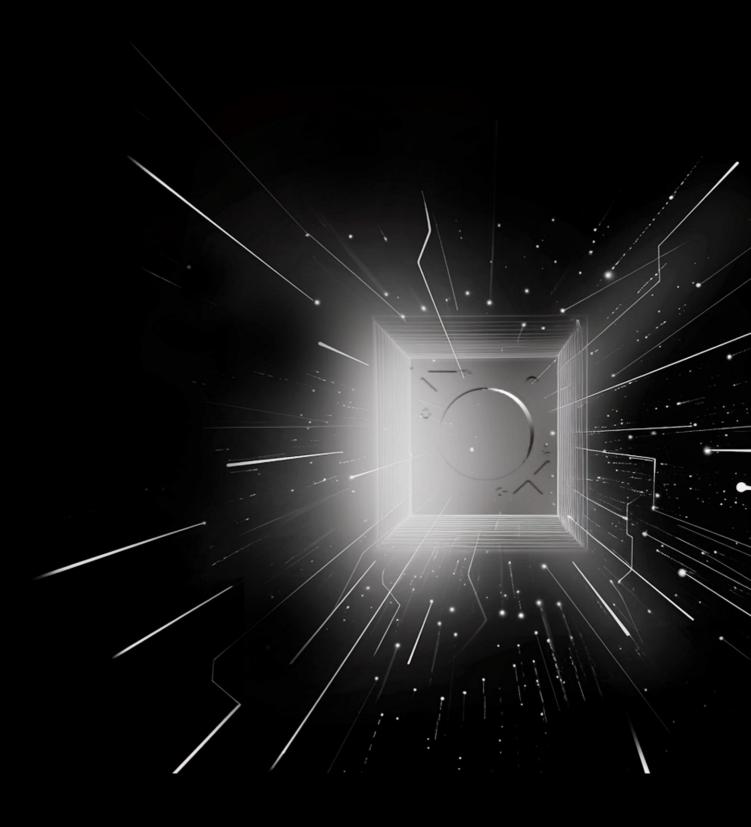


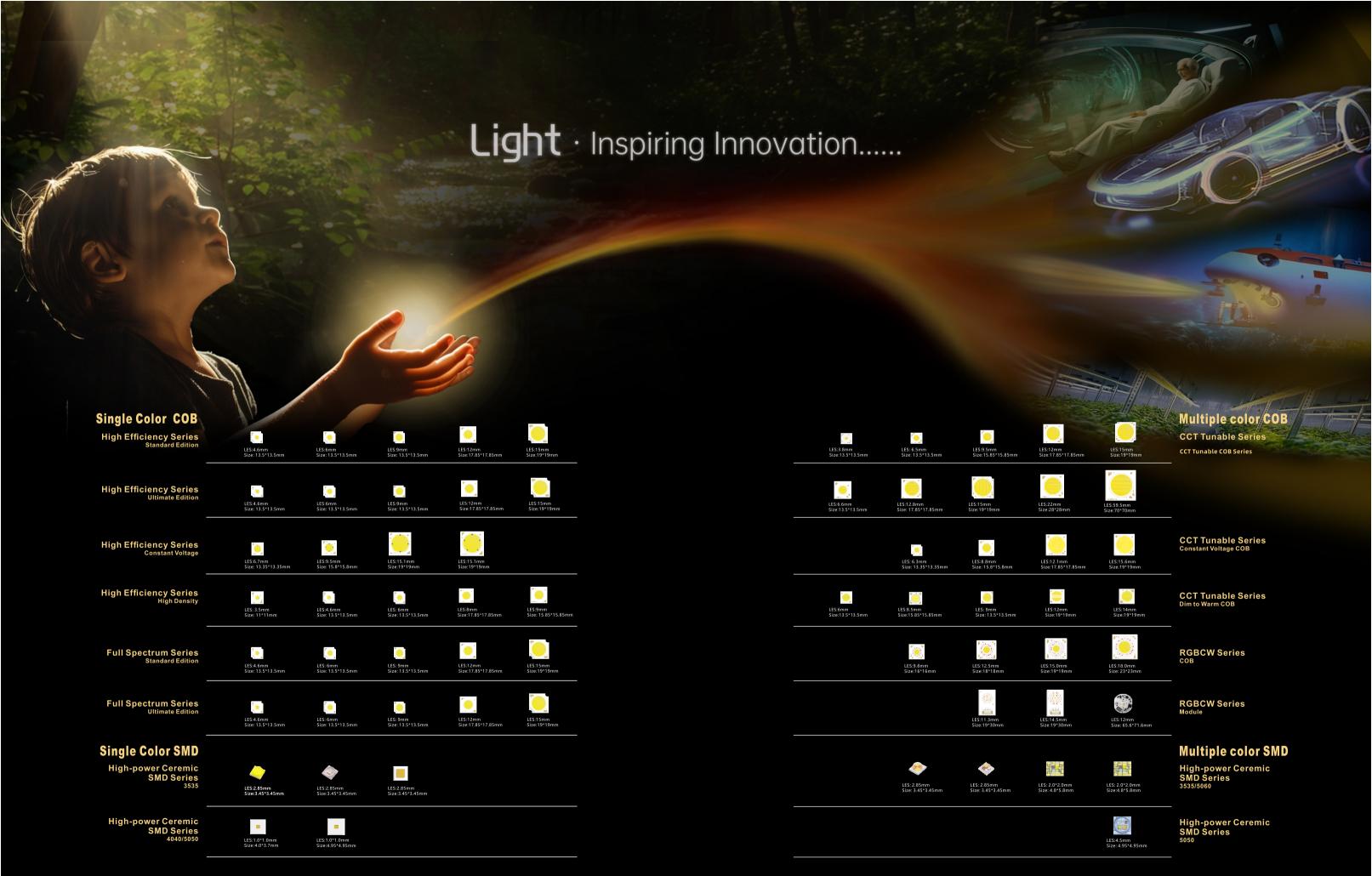














### **Company Profile**

Company Name: Foshan Evercore Optoelectronic Technology Co, Ltd.

**Headquarters**: Foshan, Guangdong Province **Production Base**: Longyan, Fujian Province

R & D platform : Evercore & Sun Yat-sen University Chip and photoelectric integration joint laboratory

Established:

Registered capital:

Patents:

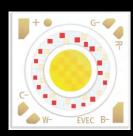
2010

11,000,000

100+

### **Market Focus**

Product focus: Photoelectric integrated module COB Market area: Commercial Lighting & Special Lighting









#### **Patent Overview**

Multiple Structure LED Chips Integrated Packaging technology patent

Multiple wavelengths Full spectrum COB Packaging technology patent

LED Integrated Light Source Modular Technology patent

Thermal isolation phosphor coatingtechnology patent

Light source module technology patent

CSC Chip-Scale phosphor coating technology

















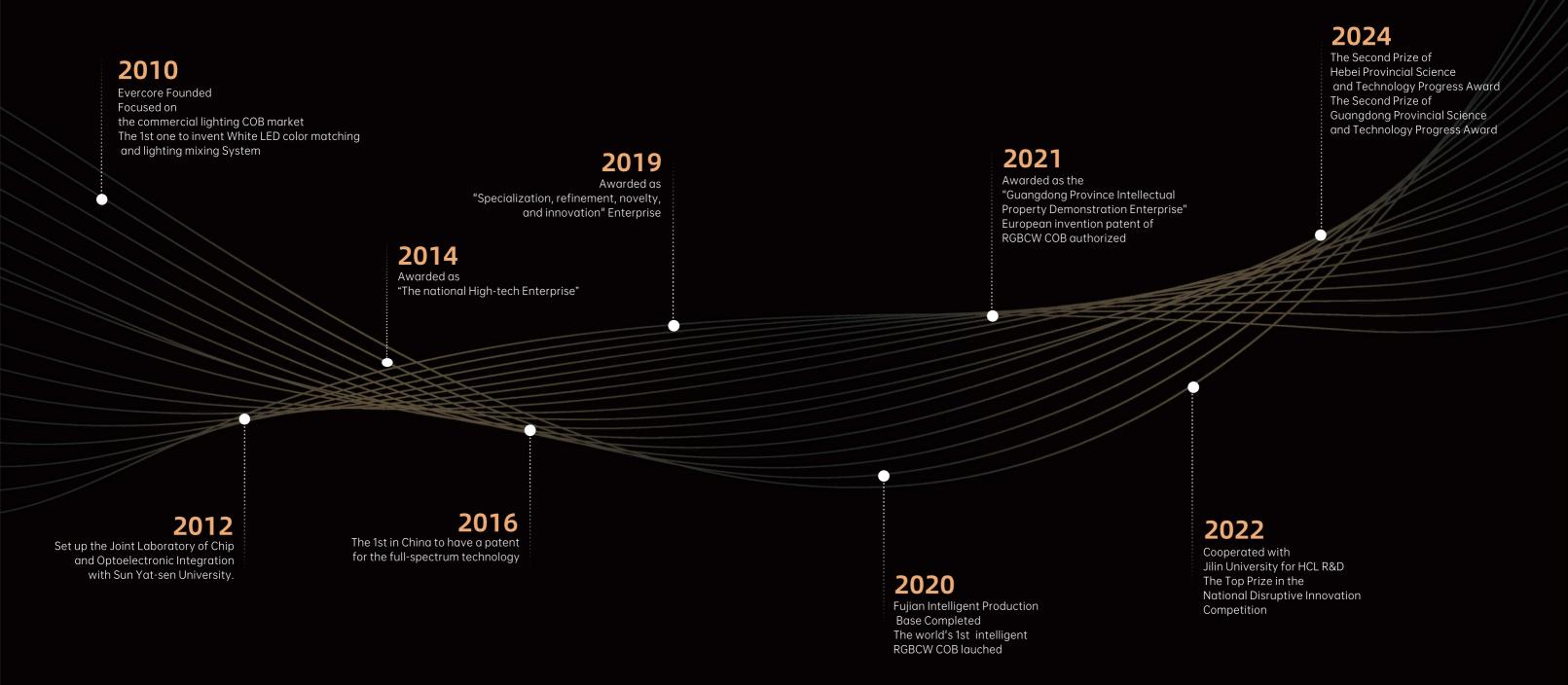
## **Quality System**

ISO9001:201 Quality Management System IES LM-80 Certification EN62471 Certification





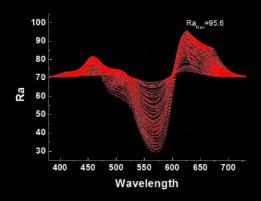
# TEVER Company History



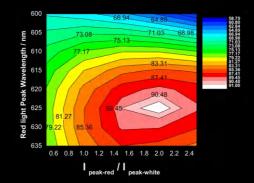
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## Core technologies

#### LED light and color mixing software system



More than 90,000 spectral configurations can be simulated, enabling mass manufacturing of unique spectral customization to satisfy the saturation and fidelity application of specific and targeted objects and space scenes.



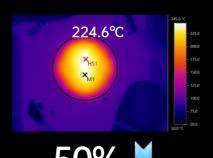
Simulate the white light effect after mixing according to the parameters of blue chip and phosphor, greatly reducing the sample customization cycle, while solving the problem of light color difference between different materials.

#### Thermal isolation phosphor coating technology

#### **Conventional COB process**



When the COB light source is working, both the phosphor and the silica gel will absorb a part of the blue light and convert it into heat. In addition, the heat capacity and thermal conductivity of the silica gel are relatively low, resulting in a sharp rise in the temperature of the fluorescent glue.



Heat dissipation performance can be improved

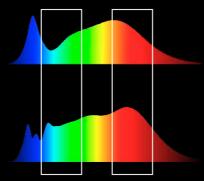




Adopting the centrifugal sedimentation method to reduce the thickness of the phosphor layer in the fluorescent glue, effectively solving the heat dissipation problem of the phosphor. The heat dissipation performance can be improved by 50%. Meanwhile, compared with the natural sedimentation process, it can save five times the time.



#### Full spectrum technology



- Excited by multiple- wavelengths blue LED chip, matched with phosphor, under the premise of completely no UV light, to simulate the full spectrum of halogen lamp effect, more fitting the solar spectrum.
- It makes up for the lack of color performance from blue to green in traditional COB products, and can truly show the purity of the light color system represented by indigo blue and the natural purity of white.
- Supplementing the 650nm long red light and 480nm long blue light band can promote the secretion of dopamine in the retina in the field of human health, which promote the improvement of scleral elasticity, and inhibit the abnormal growth of the eye axis.

#### CSC chip-level phosphor coating technology

Take into account the three-dimensional balance of light effect, light spot and power density and massproduction of process technology



Ead light spot effect, eliminated from the market.



Strip chip Array
High efficiency but
with average light
spot effect, lower
power density.



Elip chip Mosaic Array
Lower efficiency but
with good light spot
effect and higher
power density.



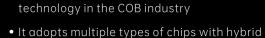
Wire bond Mosaic Array
Higher efficiency with

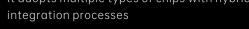
Higher efficiency with good light spot effect and higher power density.

### Multi-color chip integration & light mixing technology



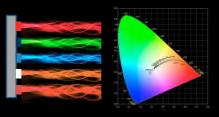






• Representing the highest level of integration

• Including wire bonding and flip-chip bonding technology



- With proprietary R&D, it incorporates a multi-channel mixed-light fitting algorithm
- Precisely output RGBCW current for each channel based on customers color requirements
- Achieving full-color gamut dimming and color tuning

## **Application focus**

## **General Lighting**



High-end commercial lighting



Commercial supermarket lighting



High-end store lighting



IOT human centric lighting

## Special lighting



Automotive lighting



Portable lighting



Plant lighting



Marine lighting

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Dim to Warm COB	18

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## **High power Ceramic SMD**

Single color SMD	2
Multiple color SMD	2